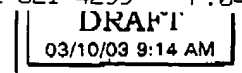


Appl. No. 09/827,741



1. (Amended) A device for cooling electronics comprising
 - (a) a container having a receptacle for receiving an electronic device, the container defining a chamber that is partially filled with a liquid coolant, wherein the receptacle is disposed between the electronic device and the chamber; the container also being capable of receiving a cooling conduit;
 - (b) a wick structure positioned within the container.
10. (Amended) A method for cooling electronics comprising:
 - (a) providing a container having a receptacle for receiving an electronic device, the container defining a chamber and having an inner wall and an outer wall;
 - (b) filling the container partially with a liquid coolant such that the liquid coolant does not contact both the inner wall and the outer wall simultaneously;
 - (c) providing an electronic device;
 - (d) connecting the electronic device to the receptacle of the container, wherein the receptacle is disposed between the electronic device and the chamber;
 - (e) generating heat by the electronic device;
 - (f) transferring heat to the coolant;
 - (g) connecting a cooling conduit to the container;
 - (h) forcing air or liquid through the cooling conduit.